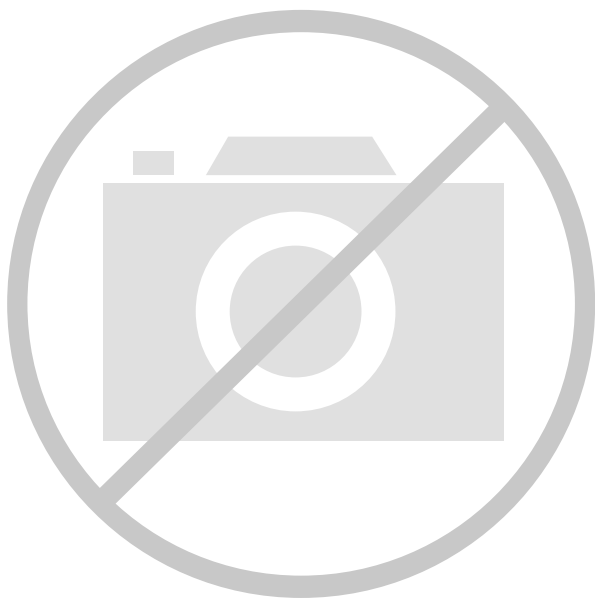




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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

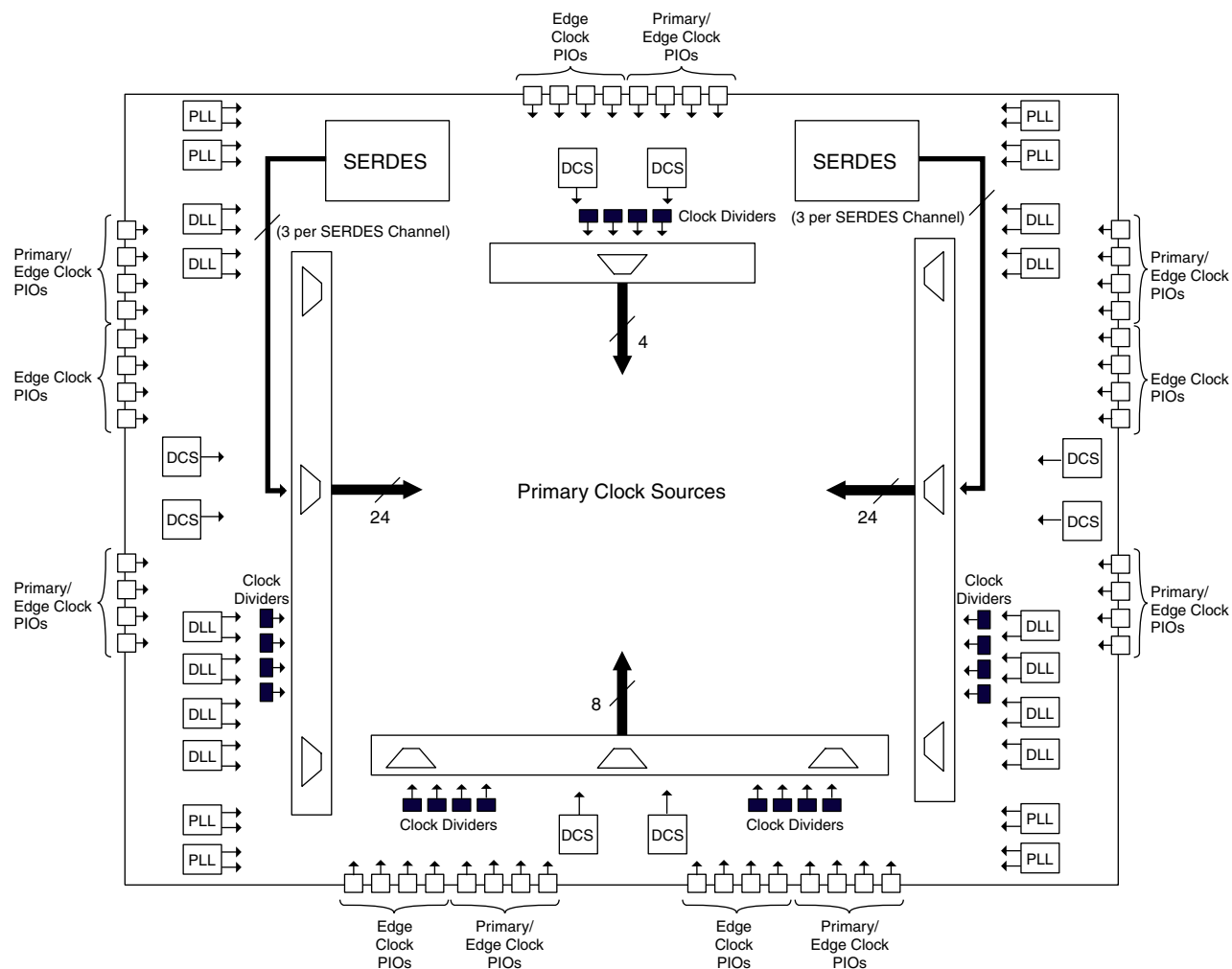
Details

Product Status	Obsolete
Number of LABs/CLBs	20000
Number of Logic Elements/Cells	80000
Total RAM Bits	5816320
Number of I/O	904
Number of Gates	-
Voltage - Supply	0.95V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1704-BBGA, FCBGA
Supplier Device Package	1704-OFCBGA (42.5x42.5)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfscm3ga80ep1-5ffn1704c

- Two outputs per PLL
- Clock divider outputs
- Digital Clock Select (DCS) block outputs
- Three outputs per SERDES quad

Figure 2-5 shows the arrangement of the primary clock sources.

Figure 2-5. Clock Sources

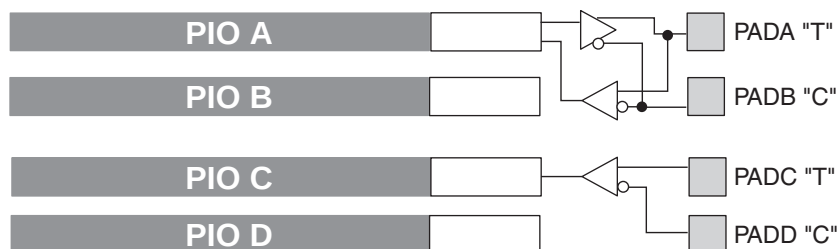


Primary Clock Routing

The clock routing structure in LatticeSC devices consists of 12 Primary Clock lines per quadrant. The primary clocks are generated from 64:1 MUXs located in each quadrant. Three of the inputs to each 64:1 MUX comes from local routing, one is connected to GND and rest of the 60 inputs are from the primary clock sources. Figure 2-6 shows this clock routing.

high-speed interfaces in the LatticeSC devices. Figure 2-18 shows how differential receivers and drivers are arranged between PIOs.

Figure 2-18. Differential Drivers and Receivers



*Differential Driver only available on right and left of the device.

PIO

The PIO contains five blocks: an input register block, output register block, tristate register block, update block, and a control logic block. These blocks contain registers for both single data rate (SDR), double data rate (DDR), and shift register operation along with the necessary clock and selection logic.

Input Register Block

The input register block contains delay elements and registers that can be used to condition signals before they are passed to the device core. Figure 2-20 show the diagram of the input register block. The signal from the PURE-SPEED I/O buffer (DI) enters the input register block and can be used for three purposes, as a source for the combinatorial (INDD) and clock outputs (INCK), the input into the SDR register/latch block and the input to the delay block. The output of the delay block can be used as combinatorial (INDD) and clock (INCK) outputs, an input to the DDR/Shift Register Block or an input into the SDR register block.

Input SDR Register/Latch Block

The SDR register/latch block has a latch and a register/latch that can be used in a variety of combinations to provide a registered or latched output (INFF). The latch operates off high-speed input clocks and latches data on the positive going edge. The register/latch operates off the low-speed input clock and registers/latches data on the positive going edge. Both the latch and the register/latch have a clock enable input that is driven by the input clock enable. In addition both have a variety of programmable options for set/reset including, set or reset, asynchronous or synchronous Local Set Reset LSR (LSR has precedence over CE) and Global Set Reset GSR enable or disable. The register and latch LSR inputs are driven from LSRI, which is generated from the PIO control MUX. The GSR inputs are driven from the GSR output of the PIO control MUX, which allows the global set-reset to be disabled on a PIO basis.

Input Delay Block

The delay block uses 144 tapped delay lines to obtain coarse and fine delay resolution. These delays can be adjusted during configuration or automatically via DLL or AIL blocks. The Adaptive Input Logic (AIL) uses this delay block to adjust automatically the delay in the data path to ensure that it has sufficient setup and hold time.

The delay line in this block matches the delay line that is used in the 12 on-chip DLLs. The delay line can be set via configuration bits or driven from a calibration bus that allows the setting to be controlled either from one of the on-chip DLLs or user logic. Controlling the delay from one of the on-chip DLLs allow the delay to be calibrated to the DLL clock and hence compensated for the variations in process, voltage and temperature.

Table 2-10. Supported Output Standards⁴

Output Standard	Drive	V _{CCIO} (Nom)	On-chip Output Termination
Single-ended Interfaces			
LVTTL/D ¹	8mA, 16mA, 24mA	3.3	None.
LVC MOS33/D ¹	8mA, 16mA, 24mA	3.3	None
LVC MOS25/D ^{1,2}	4mA, 8mA, 12mA, 16mA,	2.5	None, series: 25, 33, 50, 100
LVC MOS18/D ^{1,2}	4mA, 8mA, 12mA, 16mA,	1.8	None, series: 25, 33, 50, 100
LVC MOS15/D ^{1,2}	4mA, 8mA, 12mA, 16mA,	1.5	None, series: 25, 33, 50, 100
LVC MOS12/D ^{1,2}	2mA, 4mA, 8mA, 12mA	1.2	None, series: 25, 33, 50, 100
PCIX15	N/A	1.5	None
PCI33, PCIX33, AGP1X33, AGP2X33	N/A	3.3	None
HSTL18_I	N/A	1.8	None, series: 50
HSTL18_II	N/A	1.8	None, series: 25, series + parallel to V _{CCIO} /2: 25 + 60
HSTL15_I	N/A	1.5	None, series: 50
HSTL15_II	N/A	1.5	None, series: 25, series + parallel to V _{CCIO} /2: 25 + 60
SSTL33_I	N/A	3.3	None
SSTL33_II	N/A	3.3	None
SSTL25_I	N/A	2.5	None, series: 50
SSTL25_II	N/A	2.5	None, series: 33, series + parallel to V _{CCIO} /2: 33+ 60
SSTL18_I	N/A	1.8	None, series: 33
SSTL18_II	N/A	1.8	None, series: 33, series + parallel to V _{CCIO} /2: 33+ 60
Differential Interfaces			
SSTL18D_I	N/A	1.8	None, series: 33
SSTL25D_I	N/A	2.5	None, series: 50
SSTL18D_II, SSTL25D_II	N/A	1.2/2.5/3.3	None, series: 33, series + parallel to V _{CCIO} /2: 33+ 60
SSTL33D_I, II	N/A	3.3	None
HSTL15D_I, HSTL18D_I	N/A	1.5/1.8	None, series: 50
HST15D_II, HSTL18D_II	N/A	1.5/1.8	None, series: 25, series + parallel to V _{CCIO} /2: 25 + 60
LVDS	2mA, 3.5mA, 4mA, 6mA	N/A	None
Mini-LVDS	3.5mA, 4mA, 6mA	N/A	None
BLVDS25	N/A	N/A	None
MLVDS25	N/A	N/A	None
LVPECL33 ³	N/A	3.3	None
RSDS	2mA, 3.5mA, 4mA, 6mA	N/A	None

1. D refers to open drain capability.

2. User can select either drive current or driver impedances but not both.

3. Emulated with external resistors.

4. No GTL or GTL+ support.

PCI Clamp

A programmable PCI clamp is available on the top and bottom banks of the device. The PCI clamp can be turned “ON” or “OFF” on each pin independently. The PCI clamp is used when implementing a 3.3V PCI interface. The

Internal Logic Analyzer Capability (ispTRACY)

All LatticeSC devices support an internal logic analyzer diagnostic feature. The diagnostic features provide capabilities similar to an external logic analyzer, such as programmable event and trigger condition and deep trace memory. This feature is enabled by Lattice's ispTRACY. The ispTRACY utility is added into the user design at compile time. For additional detail refer to technical information at the end of the data sheet.

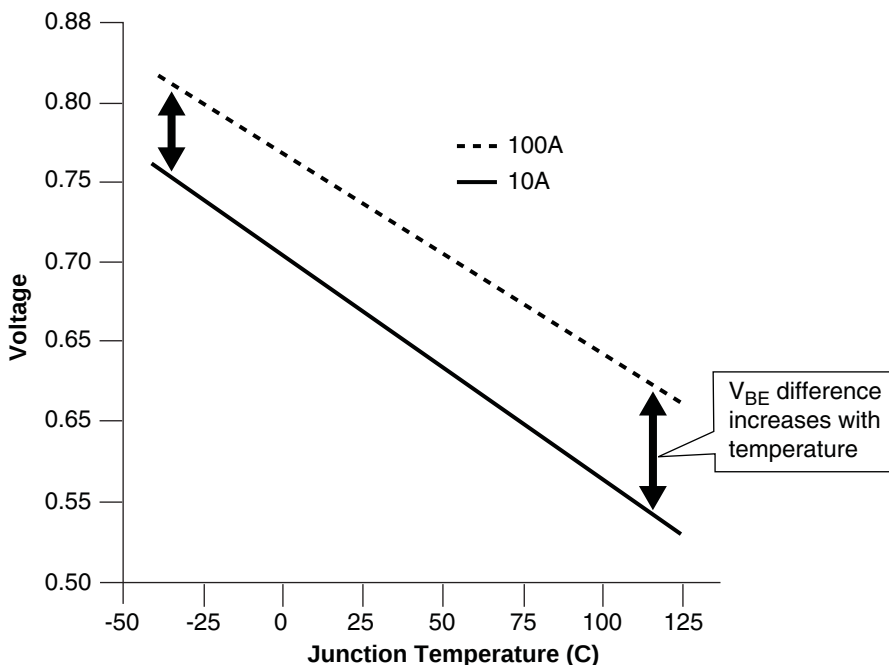
Temperature Sensing

Lattice provides a way to monitor the die temperature by using a temperature-sensing diode that is designed into every LatticeSC device. The difference in V_{BE} of the diode at two different forward currents varies with temperature. This relationship is shown in Figure 2-33. The accuracy of the temperature-sensing diode is typically $\pm 10^{\circ}\text{C}$.

On packages that include PROBE_GND, the most accurate measurements will occur between the TEMP pin and the PROBE_GND pin. On packages that do not include PROBE_GND, measurements should be made between the TEMP pin and board ground.

This temperature-sensing diode is designed to work with an external temperature sensor such as the Maxim 1617A. The Maxim 1617A is configured to measure difference in V_{BE} (of the temperature-sensing diode) at $10\mu\text{A}$ and at $100\mu\text{A}$. This difference in V_{BE} voltage varies with temperature at approximately $1.64\text{ mV}/^{\circ}\text{C}$. A typical device with a 85°C junction temperature will measure approximately 593mV . For additional detail refer to TN1115, [Temperature Sensing Diode in LatticeSC Devices](#).

Figure 2-33. Sensing Diode Typical Characteristics



Oscillator

Every LatticeSC device has an internal CMOS oscillator, which is used as a master serial clock for configuration and is also available as a potential general purpose clock (MCK) for the FPGA core. There is a K divider (divide by 2/4/8/16/32/64/128) available with this oscillator to get lower MCK frequencies. This clock is available as a general purpose clock signal to the software routing tool. For additional detail refer to technical information at the end of the data sheet.

Power Supply Ramp Rates

Symbol	Parameter	Condition	Min.	Typ.	Max	Units
t_{RAMP}	Power supply ramp rates for all power supplies	Over process, voltage, temperature	3.45	—	—	mV/ μ s
			—	—	75	ms

1. See the Power-up and Power-Down requirements section for more details on power sequencing.
2. From 0.5V to minimum operating voltage.

Hot Socketing Specifications¹

Symbol	Parameter	Condition	Min.	Typ.	Max	Units
I_{DK}	Programmable and dedicated Input or I/O leakage current ^{2, 3, 4, 5, 6}	$0 \leq V_{\text{IN}} \leq V_{\text{IH}} (\text{MAX})$	—	—	± 1500	μ A
I_{HDIN}	SERDES average input current when device powered down and inputs driven ⁷		—	—	4	mA

1. See Hot Socket power up/down information in Chapter 2 of this document.
2. Assumes monotonic rise/fall rates for all power supplies.
3. Sensitive to power supply sequencing as described in hot socketing section.
4. Assumes power supplies are between 0 and maximum recommended operations conditions.
5. I_{DK} is additive to I_{PU} , I_{PD} or I_{BH} .
6. Represents DC conditions. For the first 20ns after hot insertion, current specification is 8 mA.
7. Assumes that the device is powered down with all supplies grounded, both P and N inputs driven by a CML driver with maximum allowed VDDOB of 1.575V, 8b/10b data and internal AC coupling.

DC Electrical Characteristics⁵

Over Recommended Operating Conditions

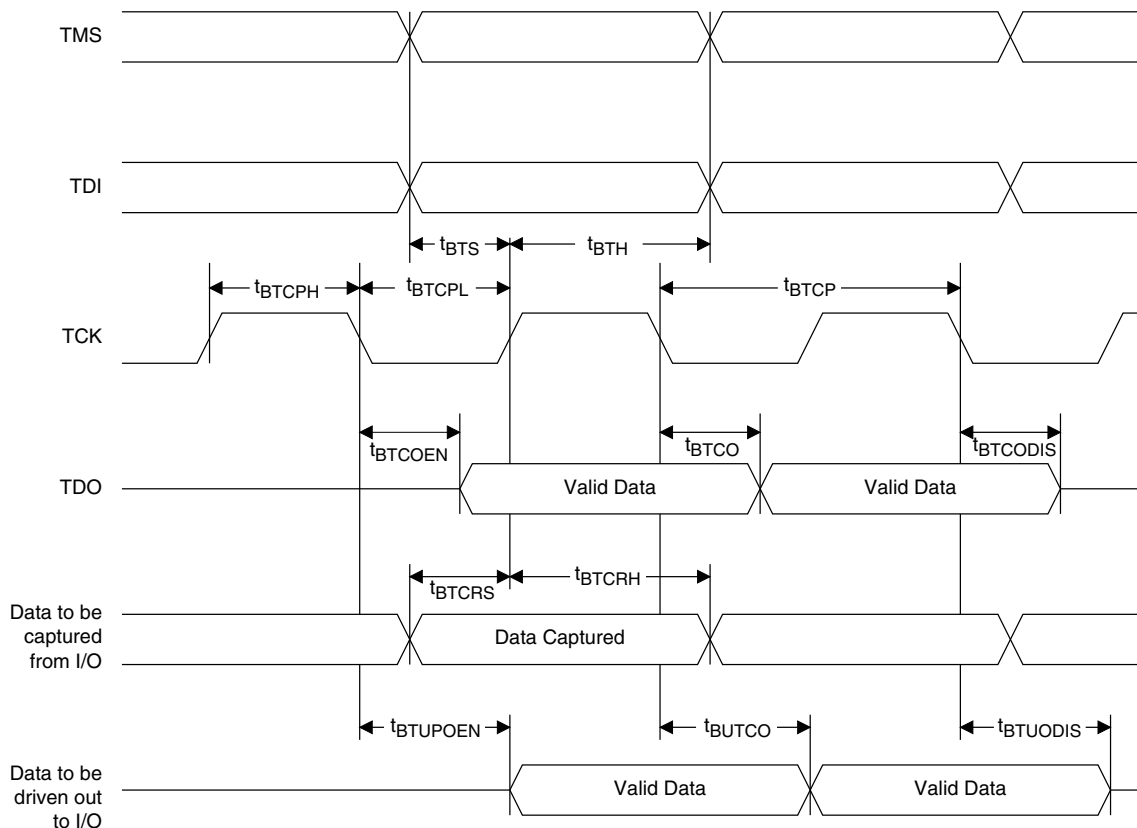
Symbol	Parameter	Condition	Min. ³	Typ.	Max.	Units
$I_{\text{IL}}, I_{\text{IH}}^1$	Input or I/O Low leakage	$0 \leq V_{\text{IN}} \leq V_{\text{IH}} (\text{MAX})$	—	—	10	μ A
I_{PU}	I/O Active Pull-up Current	$0 \leq V_{\text{IN}} \leq 0.7 V_{\text{CCIO}}$	-30	—	-210	μ A
I_{PD}	I/O Active Pull-down Current	$V_{\text{IL}} (\text{MAX}) \leq V_{\text{IN}} \leq V_{\text{IH}} (\text{MAX})$	30	—	210	μ A
I_{BHLS}	Bus Hold Low Sustaining Current	$V_{\text{IN}} = V_{\text{IL}} (\text{MAX})$	30	—	—	μ A
I_{BHHS}	Bus Hold High Sustaining Current	$V_{\text{IN}} = 0.7 V_{\text{CCIO}}$	-30	—	—	μ A
I_{BHLO}	Bus Hold Low Overdrive Current	$0 \leq V_{\text{IN}} \leq V_{\text{IH}} (\text{MAX})$	—	—	210	μ A
I_{BHLH}	Bus Hold High Overdrive Current	$0 \leq V_{\text{IN}} \leq V_{\text{IH}} (\text{MAX})$	—	—	-210	μ A
I_{CL}	PCI Low Clamp Current	$-3 < V_{\text{IN}} \leq -1$	$-25 + (V_{\text{IN}} + 1)/0.015$	—	—	mA
I_{CH}	PCI High Clamp Current	$V_{\text{CC}} + 4 > V_{\text{IN}} \geq V_{\text{CC}} + 1$	$25 + (V_{\text{IN}} - V_{\text{CC}} - 1)/0.015$	—	—	mA
V_{BHT}	Bus Hold trip Points	$0 \leq V_{\text{IN}} \leq V_{\text{IH}} (\text{MAX})$	$V_{\text{IL}} (\text{MAX})$	—	$V_{\text{IH}} (\text{MIN})$	V
C1	I/O Capacitance ²	$V_{\text{CCIO}} = 3.3\text{V}, 2.5\text{V}, 1.8\text{V}, 1.5\text{V}, 1.2\text{V},$ $V_{\text{CC}} = 1.2\text{V}, V_{\text{CCIP2}} = 1.2\text{V},$ $V_{\text{CCAUX}} = 2.5, V_{\text{IO}} = 0 \text{ to } V_{\text{IH}} (\text{MAX})$	—	8	—	pf
C3 ²	Dedicated Input Capacitance ²	$V_{\text{CCIO}} = 3.3\text{V}, 2.5\text{V}, 1.8\text{V}, 1.5\text{V}, 1.2\text{V},$ $V_{\text{CC}} = 1.2\text{V}, V_{\text{CCIP2}} = 1.2\text{V},$ $V_{\text{CCAUX}} = 2.5, V_{\text{IO}} = 0 \text{ to } V_{\text{IH}} (\text{MAX})$	—	6	—	pf

1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tri-stated. It is not measured with the output driver active. Bus maintenance circuits are disabled.
2. $T_{\text{A}} = 25^{\circ}\text{C}$, $f = 1.0\text{MHz}$
3. I_{PU} , I_{PD} , I_{BHLS} and I_{BHHS} have minimum values of 15 or -15 μ A if V_{CCIO} is set to 1.2V nominal.
4. This table does not apply to SERDES pins.
5. For programmable I/Os.

JTAG Port Timing Specifications

Over Recommended Operating Conditions

Symbol	Parameter	Min.	Max.	Units
f_{MAX}		—	25	MHz
t_{BTCP}	TCK [BSCAN] Clock Pulse Width	40	—	ns
t_{BTCPH}	TCK [BSCAN] Clock Pulse Width High	20	—	ns
t_{BTCPL}	TCK [BSCAN] Clock Pulse Width Low	20	—	ns
t_{BTS}	TCK [BSCAN] Setup Time	8	—	ns
t_{BTH}	TCK [BSCAN] Hold Time	10	—	ns
t_{BTRF}	TCK [BSCAN] Rise/Fall Time	50	—	mV/ns
t_{BTCO}	TAP Controller Falling Edge of Clock to Valid Output	—	10	ns
t_{BTCODIS}	TAP Controller Falling Edge of Clock to Valid Disable	—	10	ns
t_{BTCOEN}	TAP Controller Falling Edge of Clock to Valid Enable	—	10	ns
t_{BTCRS}	BSCAN Test Capture Register Setup Time	8	—	ns
t_{BTCRH}	BSCAN Test Capture Register Hold Time	10	—	ns
t_{BUTCO}	BSCAN Test Update Register, Falling Edge of Clock to Valid Output	—	25	ns
t_{BTUODIS}	BSCAN Test Update Register, Falling Edge of Clock to Valid Disable	—	25	ns
t_{BTUPOEN}	BSCAN Test Update Register, Falling Edge of Clock to Valid Enable	—	25	ns

Figure 3-14. JTAG Port Timing Waveforms

Switching Test Conditions

Figure 3-15 shows the output test load that is used for AC testing. The specific values for resistance, capacitance, voltage, and other test conditions are shown in Table 3-4.

Figure 3-15. Output Test Load, LVTTTL and LVCMOS Standards

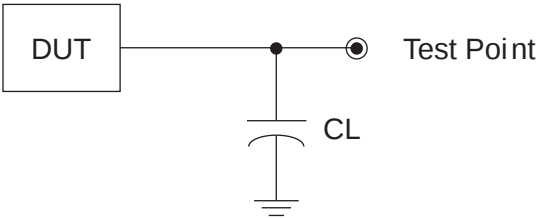


Table 3-4. Test Fixture Required Components, Non-Terminated Interfaces

Test Condition	C _L	Timing Ref.	V _T
LVTTTL and other LVCMOS settings (L -> H, H -> L)	30pF	LVCMOS 3.3 = 1.5V	—
		LVCMOS 2.5 = V _{CCIO} /2	—
		LVCMOS 1.8 = V _{CCIO} /2	—
		LVCMOS 1.5 = V _{CCIO} /2	—
		LVCMOS 1.2 = V _{CCIO} /2	—
LVCMOS 2.5 I/O (Z -> H)	30pF	V _{CCIO} /2	V _{OL}
LVCMOS 2.5 I/O (Z -> L)		V _{CCIO} /2	V _{OH}
LVCMOS 2.5 I/O (H -> Z)		V _{OH} - 0.15	V _{OL}
LVCMOS 2.5 I/O (L -> Z)		V _{OL} + 0.15	V _{OH}

Note: Output test conditions for all other interfaces are determined by the respective standards.

LFSC/M15 Logic Signal Connections: 256 fpBGA^{1,2} (Cont.)

Ball Number	LFSC/M15		
	Ball Function	VCCIO Bank	Dual Function
N12	PB39C	4	
T15	PB40A	4	PCLKT4_3
R16	PB40B	4	PCLKC4_3
L12	PB43A	4	
M12	PB43B	4	
P16	PB44A	4	
N16	PB44B	4	
R14	PB47C	4	VREF1_4
P15	PB48A	4	LRC_DLLT_IN_C/LRC_DLLT_FB_D
M13	PB48B	4	LRC_DLLC_IN_C/LRC_DLLC_FB_D
N13	PB49A	4	LRC_PLLT_IN_A/LRC_PLLT_FB_B
P14	PB49B	4	LRC_PLLC_IN_A/LRC_PLLC_FB_B
M16	PR45B	3	LRC_DLLC_IN_F/LRC_DLLC_FB_E
L16	PR45A	3	LRC_DLLT_IN_F/LRC_DLLT_FB_E
M14	PR43B	3	
M15	PR43A	3	
K16	PR41D	3	VREF2_3
J16	PR37B	3	
H16	PR37A	3	
L13	PR35D	3	DIFFR_3
L14	PR35B	3	
L15	PR35A	3	
K12	PR31C	3	VREF1_3
J13	PR28D	3	PCLKC3_2
K13	PR28C	3	PCLKT3_2
H15	PR28B	3	
F16	PR28A	3	
J11	PR26D	3	PCLKC3_1
J12	PR26C	3	PCLKT3_1
J15	PR26B	3	PCLKC3_0
J14	PR26A	3	PCLKT3_0
E16	PR24D	2	PCLKC2_2
D16	PR24C	2	PCLKT2_2
H11	PR24B	2	PCLKC2_0
H12	PR24A	2	PCLKT2_0
H13	PR23B	2	PCLKC2_1
H14	PR23A	2	PCLKT2_1
G12	PR22D	2	DIFFR_2
G13	PR22C	2	VREF1_2
F8	PR22B	2	
F9	PR22A	2	
G16	PR18D	2	VREF2_2
F15	PR17B	2	URC_DLLC_IN_C/URC_DLLC_FB_D

LFSC/M15 Logic Signal Connections: 256 fpBGA^{1,2} (Cont.)

Ball Number	LFSC/M15		
	Ball Function	VCCIO Bank	Dual Function
J9	VCC	-	
K8	VCC	-	
F6	VCC12	-	
F11	VCC12	-	
L11	VCC12	-	
L6	VCC12	-	
K7	VCC12	-	
K10	VCC12	-	
F10	VCCAUX	-	
F7	VCCAUX	-	
T1	GND	-	
G11	VCCAUX	-	
K11	VCCAUX	-	
L10	VCCAUX	-	
L9	VCCAUX	-	
L7	VCCAUX	-	
L8	VCCAUX	-	
T16	GND	-	
G6	VCCAUX	-	
K6	VCCAUX	-	
B13	VCCIO1	-	
D11	VCCIO1	-	
D14	VCCIO1	-	
F12	VCCIO2	-	
G15	VCCIO2	-	
K14	VCCIO3	-	
N15	VCCIO3	-	
M11	VCCIO4	-	
P13	VCCIO4	-	
R10	VCCIO4	-	
N6	VCCIO5	-	
P7	VCCIO5	-	
R4	VCCIO5	-	
K2	VCCIO6	-	
N3	VCCIO6	-	
F4	VCCIO7	-	
G3	VCCIO7	-	
D4	VCC12	-	
D7	VCC12	-	
D5	VCC12	-	
D6	VCC12	-	

1. Differential pair grouping within a PIC is A (True) and B (Complement) and C (True) and D (Complement).
2. The LatticeSC/M15 in a 256-pin package does not support an MPI interface.

LFSC/M15, LFSC/M25 Logic Signal Connections: 900 fpBGA^{1, 2} (Cont.)

Ball Number	LFSC/M15			LFSC/M25		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AF4	PB3C	5	LLC_DLLT_IN_C/LLC_DLLT_FB_D	PB3C	5	LLC_DLLT_IN_C/LLC_DLLT_FB_D
AE5	PB3D	5	LLC_DLLC_IN_C/LLC_DLLC_FB_D	PB3D	5	LLC_DLLC_IN_C/LLC_DLLC_FB_D
AG3	PB4A	5	LLC_DLLT_IN_D/LLC_DLLT_FB_C	PB4A	5	LLC_DLLT_IN_D/LLC_DLLT_FB_C
AH2	PB4B	5	LLC_DLLC_IN_D/LLC_DLLC_FB_C	PB4B	5	LLC_DLLC_IN_D/LLC_DLLC_FB_C
AD6	PB4C	5		PB4C	5	
AJ2	PB5A	5		PB5A	5	
AK2	PB5B	5		PB5B	5	
AD7	PB5C	5		PB5C	5	
AD8	PB5D	5	VREF1_5	PB5D	5	VREF1_5
AH3	PB7A	5		PB11A	5	
AJ3	PB7B	5		PB11B	5	
AF9	PB7C	5		PB11C	5	
AE10	PB7D	5		PB11D	5	
AK3	PB8A	5		PB12A	5	
AJ4	PB8B	5		PB12B	5	
AE11	PB9A	5		PB13A	5	
AF10	PB9B	5		PB13B	5	
AK4	PB11A	5		PB16A	5	
AK5	PB11B	5		PB16B	5	
AH10	PB12A	5	PCLKT5_3	PB20A	5	PCLKT5_3
AH11	PB12B	5	PCLKC5_3	PB20B	5	PCLKC5_3
AF13	PB12C	5	PCLKT5_4	PB20C	5	PCLKT5_4
AE14	PB12D	5	PCLKC5_4	PB20D	5	PCLKC5_4
AK6	PB13A	5	PCLKT5_5	PB21A	5	PCLKT5_5
AK7	PB13B	5	PCLKC5_5	PB21B	5	PCLKC5_5
AF14	PB13C	5		PB21C	5	
AJ11	PB15A	5	PCLKT5_0	PB23A	5	PCLKT5_0
AJ12	PB15B	5	PCLKC5_0	PB23B	5	PCLKC5_0
AH13	PB15D	5	VREF2_5	PB23D	5	VREF2_5
AK8	PB16A	5	PCLKT5_1	PB24A	5	PCLKT5_1
AK9	PB16B	5	PCLKC5_1	PB24B	5	PCLKC5_1
AH14	PB17A	5	PCLKT5_2	PB25A	5	PCLKT5_2
AG14	PB17B	5	PCLKC5_2	PB25B	5	PCLKC5_2
AK10	PB19A	5		PB28A	5	
AK11	PB19B	5		PB28B	5	
AH15	PB20A	5		PB29A	5	
AG15	PB20B	5		PB29B	5	
AH12	PB21A	5		PB31A	5	
AJ13	PB21B	5		PB31B	5	
AD15	PB21C	5		PB31C	5	
AE15	PB21D	5		PB31D	5	
AK12	PB23A	5		PB32A	5	
AK13	PB23B	5		PB32B	5	
AJ14	PB24A	5		PB33A	5	
AJ15	PB24B	5		PB33B	5	

LFSC/M15, LFSC/M25 Logic Signal Connections: 900 fpBGA^{1, 2} (Cont.)

Ball Number	LFSC/M15			LFSC/M25		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AG11	VCCIO5	-		VCCIO5	-	
AJ9	VCCIO5	-		VCCIO5	-	
AJ23	VCCIO4	-		VCCIO4	-	
AG20	VCCIO4	-		VCCIO4	-	
AJ26	VCCIO4	-		VCCIO4	-	
AG23	VCCIO4	-		VCCIO4	-	
AC29	VCCIO3	-		VCCIO3	-	
AA26	VCCIO3	-		VCCIO3	-	
Y28	VCCIO3	-		VCCIO3	-	
AA29	VCCIO3	-		VCCIO3	-	
G30	VCCIO2	-		VCCIO2	-	
J29	VCCIO2	-		VCCIO2	-	
K27	VCCIO2	-		VCCIO2	-	
N25	VCCIO2	-		VCCIO2	-	
F20	VCCIO1	-		VCCIO1	-	
C19	VCCIO1	-		VCCIO1	-	
C12	VCCIO1	-		VCCIO1	-	
F11	VCCIO1	-		VCCIO1	-	
H1	GND	-		GND	-	
L4	GND	-		GND	-	
M3	GND	-		GND	-	
N5	GND	-		GND	-	
K2	GND	-		GND	-	
M2	GND	-		GND	-	
P6	GND	-		GND	-	
G4	GND	-		GND	-	
H3	GND	-		GND	-	
AC2	GND	-		GND	-	
AA3	GND	-		GND	-	
AE1	GND	-		GND	-	
Y4	GND	-		GND	-	
AB4	GND	-		GND	-	
AA5	GND	-		GND	-	
AE6	GND	-		GND	-	
AE8	GND	-		GND	-	
AH5	GND	-		GND	-	
AG9	GND	-		GND	-	
AG6	GND	-		GND	-	
AF11	GND	-		GND	-	
AG12	GND	-		GND	-	
AJ10	GND	-		GND	-	
AK26	GND	-		GND	-	
AJ22	GND	-		GND	-	
AF20	GND	-		GND	-	
AJ25	GND	-		GND	-	

LFSC/M25, LFSC/M40 Logic Signal Connections: 1020 fcBGA^{1, 2} (Cont.)

Ball Number	LFSC/M25			LFSC/M40		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
Y24	PL48C	6		PL61C	6	
Y23	PL48D	6		PL61D	6	
AD29	PL49A	6		PL62A	6	
AD30	PL49B	6		PL62B	6	
AF28	PL49C	6		PL62C	6	
AE28	PL49D	6		PL62D	6	
AC28	PL51A	6		PL65A	6	
AD28	PL51B	6		PL65B	6	
AB26	PL51C	6		PL65C	6	
AC26	PL51D	6	VREF2_6	PL65D	6	VREF2_6
AC32	PL52A	6		PL66A	6	
AD32	PL52B	6		PL66B	6	
AA24	PL52C	6		PL66C	6	
AA23	PL52D	6		PL66D	6	
AE30	PL53A	6		PL67A	6	
AE29	PL53B	6		PL67B	6	
AC25	PL53C	6		PL67C	6	
AB25	PL53D	6		PL67D	6	
AE31	PL55A	6		PL69A	6	
AE32	PL55B	6		PL69B	6	
AE26	PL55C	6	LLC_DLLT_IN_E/LLC_DLLT_FB_F	PL69C	6	LLC_DLLT_IN_E/LLC_DLLT_FB_F
AE27	PL55D	6	LLC_DLLC_IN_E/LLC_DLLC_FB_F	PL69D	6	LLC_DLLC_IN_E/LLC_DLLC_FB_F
AF32	PL56A	6		PL70A	6	
AF31	PL56B	6		PL70B	6	
AC24	PL56C	6		PL70C	6	
AD25	PL56D	6		PL70D	6	
AG32	PL57A	6	LLC_DLLT_IN_F/LLC_DLLT_FB_E	PL71A	6	LLC_DLLT_IN_F/LLC_DLLT_FB_E
AG31	PL57B	6	LLC_DLLC_IN_F/LLC_DLLC_FB_E	PL71B	6	LLC_DLLC_IN_F/LLC_DLLC_FB_E
AC23	PL57C	6	LLC_PLLT_IN_B/LLC_PLLT_FB_A	PL71C	6	LLC_PLLT_IN_B/LLC_PLLT_FB_A
AD24	PL57D	6	LLC_PLLC_IN_B/LLC_PLLC_FB_A	PL71D	6	LLC_PLLC_IN_B/LLC_PLLC_FB_A
AH32	XRES	-		XRES	-	
AH31	TEMP	6		TEMP	6	
AJ32	PB3A	5	LLC_PLLT_IN_A/LLC_PLLT_FB_B	PB3A	5	LLC_PLLT_IN_A/LLC_PLLT_FB_B
AK32	PB3B	5	LLC_PLLC_IN_A/LLC_PLLC_FB_B	PB3B	5	LLC_PLLC_IN_A/LLC_PLLC_FB_B
AF27	PB3C	5	LLC_DLLT_IN_C/LLC_DLLT_FB_D	PB3C	5	LLC_DLLT_IN_C/LLC_DLLT_FB_D
AG28	PB3D	5	LLC_DLLC_IN_C/LLC_DLLC_FB_D	PB3D	5	LLC_DLLC_IN_C/LLC_DLLC_FB_D
AK31	PB4A	5	LLC_DLLT_IN_D/LLC_DLLT_FB_C	PB4A	5	LLC_DLLT_IN_D/LLC_DLLT_FB_C
AL31	PB4B	5	LLC_DLLC_IN_D/LLC_DLLC_FB_C	PB4B	5	LLC_DLLC_IN_D/LLC_DLLC_FB_C
AE25	PB4C	5		PB4C	5	
AE24	PB4D	5		PB4D	5	
AK30	PB5A	5		PB5A	5	
AL30	PB5B	5		PB5B	5	
AD23	PB5C	5		PB5C	5	
AE23	PB5D	5	VREF1_5	PB5D	5	VREF1_5
AK29	PB7A	5		PB7A	5	
AL29	PB7B	5		PB7B	5	
AF26	PB7C	5		PB7C	5	
AF25	PB7D	5		PB7D	5	
AJ28	PB8A	5		PB8A	5	
AK28	PB8B	5		PB8B	5	

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA^{1, 2} (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
K20	GND	-		GND	-	
K23	GND	-		GND	-	
K26	GND	-		GND	-	
K28	GND	-		GND	-	
K6	GND	-		GND	-	
K9	GND	-		GND	-	
L12	GND	-		GND	-	
L32	GND	-		GND	-	
L4	GND	-		GND	-	
M10	GND	-		GND	-	
M17	GND	-		GND	-	
M24	GND	-		GND	-	
N29	GND	-		GND	-	
N7	GND	-		GND	-	
P15	GND	-		GND	-	
P20	GND	-		GND	-	
P3	GND	-		GND	-	
P31	GND	-		GND	-	
R10	GND	-		GND	-	
R14	GND	-		GND	-	
R16	GND	-		GND	-	
R19	GND	-		GND	-	
R21	GND	-		GND	-	
R26	GND	-		GND	-	
T15	GND	-		GND	-	
T17	GND	-		GND	-	
T18	GND	-		GND	-	
T20	GND	-		GND	-	
T28	GND	-		GND	-	
T6	GND	-		GND	-	
U16	GND	-		GND	-	
U19	GND	-		GND	-	
U23	GND	-		GND	-	
U32	GND	-		GND	-	
U4	GND	-		GND	-	
V12	GND	-		GND	-	
V16	GND	-		GND	-	
V19	GND	-		GND	-	
V3	GND	-		GND	-	
V31	GND	-		GND	-	
W15	GND	-		GND	-	
W17	GND	-		GND	-	
W18	GND	-		GND	-	
W20	GND	-		GND	-	
W29	GND	-		GND	-	

LFSC/M115 Logic Signal Connections: 1152 fcBGA^{1, 2}

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
F25	B_HDINN0_L	-	PCS 361 CH 0 IN N
E25	B_HDINP0_L	-	PCS 361 CH 0 IN P
D28	B_VDDIB0_L	-	
G25	VCC12	-	
D29	A_VDDIB3_L	-	
C25	VCC12	-	
A25	A_HDINP3_L	-	PCS 360 CH 3 IN P
B25	A_HDINN3_L	-	PCS 360 CH 3 IN N
A26	A_HDOUTP3_L	-	PCS 360 CH 3 OUT P
E27	VCC12	-	
B26	A_HDOUTN3_L	-	PCS 360 CH 3 OUT N
F26	A_VDDOB3_L	-	
B27	A_HDOUTN2_L	-	PCS 360 CH 2 OUT N
F27	A_VDDOB2_L	-	
A27	A_HDOUTP2_L	-	PCS 360 CH 2 OUT P
E28	VCC12	-	
B28	A_HDINN2_L	-	PCS 360 CH 2 IN N
A28	A_HDINP2_L	-	PCS 360 CH 2 IN P
D30	A_VDDIB2_L	-	
C28	VCC12	-	
D31	A_VDDIB1_L	-	
C29	VCC12	-	
A29	A_HDINP1_L	-	PCS 360 CH 1 IN P
B29	A_HDINN1_L	-	PCS 360 CH 1 IN N
A30	A_HDOUTP1_L	-	PCS 360 CH 1 OUT P
E29	VCC12	-	
B30	A_HDOUTN1_L	-	PCS 360 CH 1 OUT N
F28	A_VDDOB1_L	-	
B31	A_HDOUTN0_L	-	PCS 360 CH 0 OUT N
F29	A_VDDOB0_L	-	
A31	A_HDOUTP0_L	-	PCS 360 CH 0 OUT P
E30	VCC12	-	
B32	A_HDINN0_L	-	PCS 360 CH 0 IN N
A32	A_HDINP0_L	-	PCS 360 CH 0 IN P
D32	A_VDDIB0_L	-	
C32	VCC12	-	
E34	PL30A	7	
F34	PL30B	7	
F33	PL34A	7	
G33	PL34B	7	
K30	PL38A	7	
L30	PL38B	7	
G34	PL40A	7	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA^{1, 2} (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
H18	PT77C	1	LDCN/SCS	PT93C	1	LDCN/SCS
F18	PT77B	1	D8/MPI_DATA8	PT93B	1	D8/MPI_DATA8
E18	PT77A	1	CS1/MPI_CS1	PT93A	1	CS1/MPI_CS1
H19	PT75D	1	D9/MPI_DATA9	PT90D	1	D9/MPI_DATA9
G19	PT75C	1	D10/MPI_DATA10	PT90C	1	D10/MPI_DATA10
D19	PT75B	1	CS0N/MPI_CS0N	PT90B	1	CS0N/MPI_CS0N
D18	PT75A	1	RDN/MPI_STRB_N	PT90A	1	RDN/MPI_STRB_N
J20	PT74D	1	WRN/MPI_WR_N	PT89D	1	WRN/MPI_WR_N
K20	PT74C	1	D7/MPI_DATA7	PT89C	1	D7/MPI_DATA7
E19	PT74B	1	D6/MPI_DATA6	PT89B	1	D6/MPI_DATA6
F19	PT74A	1	D5/MPI_DATA5	PT89A	1	D5/MPI_DATA5
K18	PT73D	1	D4/MPI_DATA4	PT87D	1	D4/MPI_DATA4
J18	PT73C	1	D3/MPI_DATA3	PT87C	1	D3/MPI_DATA3
A19	PT73B	1	D2/MPI_DATA2	PT87B	1	D2/MPI_DATA2
B19	PT73A	1	D1/MPI_DATA1	PT87A	1	D1/MPI_DATA1
H17	PT71D	1	D16/PCLKC1_3/MPI_DATA16	PT86D	1	D16/PCLKC1_3/MPI_DATA16
J17	PT71C	1	D17/PCLKT1_3/MPI_DATA17	PT86C	1	D17/PCLKT1_3/MPI_DATA17
B20	PT71B	1	D0/MPI_DATA0	PT86B	1	D0/MPI_DATA0
C20	PT71A	1	QOUT/CEON	PT86A	1	QOUT/CEON
M20	PT70D	1	VREF2_1	PT83D	1	VREF2_1
L20	PT70C	1	D18/MPI_DATA18	PT83C	1	D18/MPI_DATA18
F20	PT70B	1	DOUT	PT83B	1	DOUT
G20	PT70A	1	MCA_DONE_IN	PT83A	1	MCA_DONE_IN
K19	PT69D	1	D19/PCLKC1_2/MPI_DATA19	PT81D	1	D19/PCLKC1_2/MPI_DATA19
J19	PT69C	1	D20/PCLKT1_2/MPI_DATA20	PT81C	1	D20/PCLKT1_2/MPI_DATA20
D20	PT69B	1	MCA_CLK_P1_OUT	PT81B	1	MCA_CLK_P1_OUT
E20	PT69A	1	MCA_CLK_P1_IN	PT81A	1	MCA_CLK_P1_IN
H21	PT67D	1	D21/PCLKC1_1/MPI_DATA21	PT78D	1	D21/PCLKC1_1/MPI_DATA21
G21	PT67C	1	D22/PCLKT1_1/MPI_DATA22	PT78C	1	D22/PCLKT1_1/MPI_DATA22
B21	PT67B	1	MCA_CLK_P2_OUT	PT78B	1	MCA_CLK_P2_OUT
C21	PT67A	1	MCA_CLK_P2_IN	PT78A	1	MCA_CLK_P2_IN
M21	PT66D	1	MCA_DONE_OUT	PT75D	1	MCA_DONE_OUT
L21	PT66C	1	BUSYN/RCLK/SCK	PT75C	1	BUSYN/RCLK/SCK
A21	PT66B	1	DP0/MPI_PAR0	PT75B	1	DP0/MPI_PAR0
A20	PT66A	1	MPI_TA	PT75A	1	MPI_TA
J21	PT65D	1	D23/MPI_DATA23	PT73D	1	D23/MPI_DATA23
K21	PT65C	1	DP2/MPI_PAR2	PT73C	1	DP2/MPI_PAR2
E21	PT65B	1	PCLKC1_0	PT73B	1	PCLKC1_0
F21	PT65A	1	PCLKT1_0/MPI_CLK	PT73A	1	PCLKT1_0/MPI_CLK
G22	PT63D	1	DP3/PCLKC1_4/MPI_PAR3	PT71D	1	DP3/PCLKC1_4/MPI_PAR3
H22	PT63C	1	D24/PCLKT1_4/MPI_DATA24	PT71C	1	D24/PCLKT1_4/MPI_DATA24
A23	PT63B	1	MPI_RETRY	PT71B	1	MPI_RETRY
A22	PT63A	1	A0/MPI_ADDR14	PT71A	1	A0/MPI_ADDR14
L22	PT61D	1	A1/MPI_ADDR15	PT69D	1	A1/MPI_ADDR15
M22	PT61C	1	A2/MPI_ADDR16	PT69C	1	A2/MPI_ADDR16

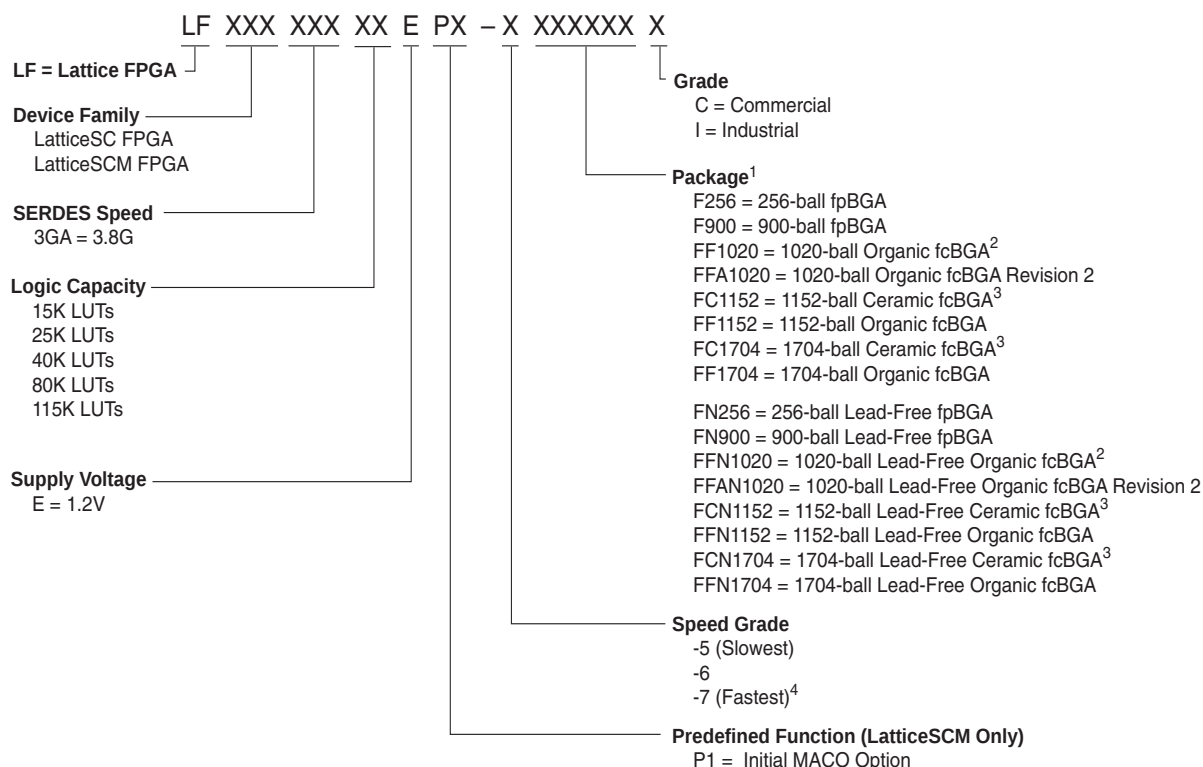
LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA^{1, 2} (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
D32	C_HDINP1_L	-	PCS 362 CH 1 IN P	C_HDINP1_L	-	PCS 362 CH 1 IN P
E32	C_HDINN1_L	-	PCS 362 CH 1 IN N	C_HDINN1_L	-	PCS 362 CH 1 IN N
B31	C_HDOUTP1_L	-	PCS 362 CH 1 OUT P	C_HDOUTP1_L	-	PCS 362 CH 1 OUT P
K32	VCC12	-		VCC12	-	
A31	C_HDOUTN1_L	-	PCS 362 CH 1 OUT N	C_HDOUTN1_L	-	PCS 362 CH 1 OUT N
L32	C_VDDOB1_L	-		C_VDDOB1_L	-	
A32	C_HDOUTN0_L	-	PCS 362 CH 0 OUT N	C_HDOUTN0_L	-	PCS 362 CH 0 OUT N
M31	C_VDDOB0_L	-		C_VDDOB0_L	-	
B32	C_HDOUTP0_L	-	PCS 362 CH 0 OUT P	C_HDOUTP0_L	-	PCS 362 CH 0 OUT P
H37	VCC12	-		VCC12	-	
E33	C_HDINN0_L	-	PCS 362 CH 0 IN N	C_HDINN0_L	-	PCS 362 CH 0 IN N
D33	C_HDINP0_L	-	PCS 362 CH 0 IN P	C_HDINP0_L	-	PCS 362 CH 0 IN P
G31	C_VDDIB0_L	-		C_VDDIB0_L	-	
J29	VCC12	-		VCC12	-	
L29	B_REFCLKP_L	-		B_REFCLKP_L	-	
M29	B_REFCLKN_L	-		B_REFCLKN_L	-	
J31	VCC12	-		VCC12	-	
H31	B_VDDIB3_L	-		B_VDDIB3_L	-	
J30	VCC12	-		VCC12	-	
D34	B_HDINP3_L	-	PCS 361 CH 3 IN P	B_HDINP3_L	-	PCS 361 CH 3 IN P
E34	B_HDINN3_L	-	PCS 361 CH 3 IN N	B_HDINN3_L	-	PCS 361 CH 3 IN N
B33	B_HDOUTP3_L	-	PCS 361 CH 3 OUT P	B_HDOUTP3_L	-	PCS 361 CH 3 OUT P
H38	VCC12	-		VCC12	-	
A33	B_HDOUTN3_L	-	PCS 361 CH 3 OUT N	B_HDOUTN3_L	-	PCS 361 CH 3 OUT N
C38	B_VDDOB3_L	-		B_VDDOB3_L	-	
A34	B_HDOUTN2_L	-	PCS 361 CH 2 OUT N	B_HDOUTN2_L	-	PCS 361 CH 2 OUT N
L31	B_VDDOB2_L	-		B_VDDOB2_L	-	
B34	B_HDOUTP2_L	-	PCS 361 CH 2 OUT P	B_HDOUTP2_L	-	PCS 361 CH 2 OUT P
G38	VCC12	-		VCC12	-	
E35	B_HDINN2_L	-	PCS 361 CH 2 IN N	B_HDINN2_L	-	PCS 361 CH 2 IN N
D35	B_HDINP2_L	-	PCS 361 CH 2 IN P	B_HDINP2_L	-	PCS 361 CH 2 IN P
H32	B_VDDIB2_L	-		B_VDDIB2_L	-	
K29	VCC12	-		VCC12	-	
K30	B_VDDIB1_L	-		B_VDDIB1_L	-	
F33	VCC12	-		VCC12	-	
D36	B_HDINP1_L	-	PCS 361 CH 1 IN P	B_HDINP1_L	-	PCS 361 CH 1 IN P
E36	B_HDINN1_L	-	PCS 361 CH 1 IN N	B_HDINN1_L	-	PCS 361 CH 1 IN N
B35	B_HDOUTP1_L	-	PCS 361 CH 1 OUT P	B_HDOUTP1_L	-	PCS 361 CH 1 OUT P
L34	VCC12	-		VCC12	-	
A35	B_HDOUTN1_L	-	PCS 361 CH 1 OUT N	B_HDOUTN1_L	-	PCS 361 CH 1 OUT N
K35	B_VDDOB1_L	-		B_VDDOB1_L	-	
A36	B_HDOUTN0_L	-	PCS 361 CH 0 OUT N	B_HDOUTN0_L	-	PCS 361 CH 0 OUT N
G39	B_VDDOB0_L	-		B_VDDOB0_L	-	
B36	B_HDOUTP0_L	-	PCS 361 CH 0 OUT P	B_HDOUTP0_L	-	PCS 361 CH 0 OUT P
J35	VCC12	-		VCC12	-	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA^{1, 2} (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AM27	GND	-		GND	-	
AM36	GND	-		GND	-	
AM7	GND	-		GND	-	
AP4	GND	-		GND	-	
AP40	GND	-		GND	-	
AR14	GND	-		GND	-	
AR20	GND	-		GND	-	
AR23	GND	-		GND	-	
AR29	GND	-		GND	-	
AR35	GND	-		GND	-	
AR8	GND	-		GND	-	
AT11	GND	-		GND	-	
AT17	GND	-		GND	-	
AT26	GND	-		GND	-	
AT32	GND	-		GND	-	
AU3	GND	-		GND	-	
AU39	GND	-		GND	-	
AW12	GND	-		GND	-	
AW18	GND	-		GND	-	
AW22	GND	-		GND	-	
AW28	GND	-		GND	-	
AW34	GND	-		GND	-	
AW6	GND	-		GND	-	
AY15	GND	-		GND	-	
AY21	GND	-		GND	-	
AY25	GND	-		GND	-	
AY31	GND	-		GND	-	
AY37	GND	-		GND	-	
AY9	GND	-		GND	-	
B1	GND	-		GND	-	
B42	GND	-		GND	-	
BA1	GND	-		GND	-	
BA42	GND	-		GND	-	
BB2	GND	-		GND	-	
BB41	GND	-		GND	-	
C10	GND	-		GND	-	
C12	GND	-		GND	-	
C13	GND	-		GND	-	
C16	GND	-		GND	-	
C18	GND	-		GND	-	
C19	GND	-		GND	-	
C22	GND	-		GND	-	
C24	GND	-		GND	-	
C27	GND	-		GND	-	
C28	GND	-		GND	-	

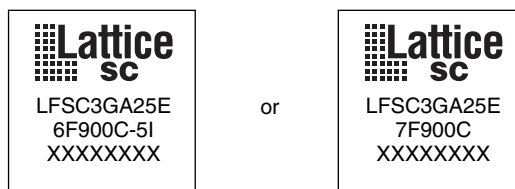
Part Number Description



1. fpBGA = 1.0 mm pitch BGA, fcBGA = 1.0 mm flip-chip BGA (organic and ceramic).
2. Converted to organic fcBGA per PCN #02A-10.
3. Converted to organic fcBGA per PCN #01A-10.
4. Not available in the LatticeSC115 and LatticeSCM115 devices.

Ordering Information

Depending on the speed and temperature grade, the device can either be dual marked or single marked. The commercial grade is one speed grade faster than the associated dual marked industrial grade. The slowest commercial speed grade does not have industrial markings. The markings appear as follows:



Temperature Grade	Speed Grade	Single or Dual Mark?
Commercial	-7	Either OK
	-6	Dual Only
	-5	Single Only
Industrial	-6	Either OK
	-5	Dual Only

Commercial, Cont.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA40E-7FF1020C ¹	-7	Organic fcBGA	1020	COM	40.4
LFSC3GA40E-6FF1020C ¹	-6	Organic fcBGA	1020	COM	40.4
LFSC3GA40E-5FF1020C ¹	-5	Organic fcBGA	1020	COM	40.4
LFSC3GA40E-7FFA1020C	-7	Organic fcBGA Revision 2	1020	COM	40.4
LFSC3GA40E-6FFA1020C	-6	Organic fcBGA Revision 2	1020	COM	40.4
LFSC3GA40E-5FFA1020C	-5	Organic fcBGA Revision 2	1020	COM	40.4
LFSC3GA40E-7FC1152C ²	-7	Ceramic fcBGA	1152	COM	40.4
LFSC3GA40E-6FC1152C ²	-6	Ceramic fcBGA	1152	COM	40.4
LFSC3GA40E-5FC1152C ²	-5	Ceramic fcBGA	1152	COM	40.4
LFSC3GA40E-7FF1152C	-7	Organic fcBGA	1152	COM	40.4
LFSC3GA40E-6FF1152C	-6	Organic fcBGA	1152	COM	40.4
LFSC3GA40E-5FF1152C	-5	Organic fcBGA	1152	COM	40.4

1. Converted to organic flip-chip BGA package revision 2 per [PCN #02A-10](#).

2. Converted to organic flip-chip BGA package per [PCN #01A-10](#).

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA40EP1-7FF1020C ¹	-7	Organic fcBGA	1020	COM	40.4
LFSCM3GA40EP1-6FF1020C ¹	-6	Organic fcBGA	1020	COM	40.4
LFSCM3GA40EP1-5FF1020C ¹	-5	Organic fcBGA	1020	COM	40.4
LFSCM3GA40EP1-7FFA1020C	-7	Organic fcBGA Revision 2	1020	COM	40.4
LFSCM3GA40EP1-6FFA1020C	-6	Organic fcBGA Revision 2	1020	COM	40.4
LFSCM3GA40EP1-5FFA1020C	-5	Organic fcBGA Revision 2	1020	COM	40.4
LFSCM3GA40EP1-7FC1152C ²	-7	Ceramic fcBGA	1152	COM	40.4
LFSCM3GA40EP1-6FC1152C ²	-6	Ceramic fcBGA	1152	COM	40.4
LFSCM3GA40EP1-5FC1152C ²	-5	Ceramic fcBGA	1152	COM	40.4
LFSCM3GA40EP1-7FF1152C	-7	Organic fcBGA	1152	COM	40.4
LFSCM3GA40EP1-6FF1152C	-6	Organic fcBGA	1152	COM	40.4
LFSCM3GA40EP1-5FF1152C	-5	Organic fcBGA	1152	COM	40.4

1. Converted to organic flip-chip BGA package revision 2 per [PCN #02A-10](#).

2. Converted to organic flip-chip BGA package per [PCN #01A-10](#).

Industrial, Cont.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA115E-6FC1152I ¹	-6	Ceramic fcBGA	1152	IND	115.2
LFSC3GA115E-5FC1152I ¹	-5	Ceramic fcBGA	1152	IND	115.2
LFSC3GA115E-6FF1152I	-6	Organic fcBGA	1152	IND	115.2
LFSC3GA115E-5FF1152I	-5	Organic fcBGA	1152	IND	115.2
LFSC3GA115E-6FC1704I ¹	-6	Ceramic fcBGA	1704	IND	115.2
LFSC3GA115E-5FC1704I ¹	-5	Ceramic fcBGA	1704	IND	115.2
LFSC3GA115E-6FF1704I	-6	Organic fcBGA	1704	IND	115.2
LFSC3GA115E-5FF1704I	-5	Organic fcBGA	1704	IND	115.2

1. Converted to organic flip-chip BGA package per [PCN #01A-10](#).

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA115EP1-6FC1152I ¹	-6	Ceramic fcBGA	1152	IND	115.2
LFSCM3GA115EP1-5FC1152I ¹	-5	Ceramic fcBGA	1152	IND	115.2
LFSCM3GA115EP1-6FF1152I	-6	Organic fcBGA	1152	IND	115.2
LFSCM3GA115EP1-5FF1152I	-5	Organic fcBGA	1152	IND	115.2
LFSCM3GA115EP1-6FC1704I ¹	-6	Ceramic fcBGA	1704	IND	115.2
LFSCM3GA115EP1-5FC1704I ¹	-5	Ceramic fcBGA	1704	IND	115.2
LFSCM3GA115EP1-6FF1704I	-6	Organic fcBGA	1704	IND	115.2
LFSCM3GA115EP1-5FF1704I	-5	Organic fcBGA	1704	IND	115.2

1. Converted to organic flip-chip BGA package per [PCN #01A-10](#).